

PATENTS ONLY (ref OG 7/28/92)

06-16-2003



To the Honorable Commiss:
Please record the attached

102473977 .. reof.

1. Name of Party(ies) conveying an interest:

Yoshihiro IWAI
Tatsuki ISHII
Kenji SHIGEOKA
Hirotake TOKUYAMA

2. Name and Address of Party(ies) receiving an interest:

HITACHI, LTD.
6, Kanda Surugadai 4-chome
Chiyoda-ku, Tokyo, JAPAN

HITACHI INFORMATION TECHNOLOGY CO., LTD.
456, Sakai, Nakai-machi, Ashigarakami-gun
Kanagawa, JAPAN

3. Description of the interest conveyed: Assignment

4. Application number(s) or patent number(s).

Additional sheet attached? ___ Yes XXX No

If this document is being filed together with a new application,
the execution date of the application is: _____

DATE

A. Patent Application No.(s)

10/393,921

B. Patent No.(s)

5. Name and address of party to whom correspondence concerning document should be mailed:

John R. Mattingly
Mattingly, Stanger & Malur, P.C.
1800 Diagonal Road, Suite 370
Alexandria, Virginia 22314

6. Number of applications and patents involved: One

7. Amount of fee enclosed or authorized to be charged: \$40.00

8. The Commissioner is hereby authorized to charge Deposit Account No. 50-1417 if no check is attached.

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06/11/2003 ANONDAF2 00000180 10393921

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40.00 OP

9. Execution date of attached document: May 29, 2003

10. To the best of my knowledge and belief, I declare under penalty of perjury under the laws of the United States of America that the foregoing information is true and correct and that any attached copy is a true copy of the original document.

Daniel J. Stanger
Name of Person Signing

Signature

June 10, 2003
Date

Total number of pages being submitted: 2

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ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd.,
and Hitachi Information Technology Co.,Ltd
corporations organized under the laws of Japan,
located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan,
and 456, Sakai, Nakai-machi, Ashigarakami-gun, Kanagawa, Japan
receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd.,
and Hitachi Information Technology Co.,Ltd
their successors and assigns, all my right, title and interest, in and for the United States of America, in and to
**DELAY DIAGNOSIS METHOD FOR SEMICONDUCTOR INTEGRATED CIRCUIT, COMPUTER
PROGRAM PRODUCT FOR DIAGNOSING DELAY OF SEMICONDUCTOR INTEGRATED
CIRCUIT AND COMPUTER READABLE RECORDING MEDIUM RECORDING PROGRAM
THEREON** *U.S. Serial No. 10/393921 filed on March 24, 2003
invented by me (if only one is named below) or us (if plural inventors are named below) and described in the
application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters
Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being
the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd.,
and Hitachi Information Technology Co.,Ltd
their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be
granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale
had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and
proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing,
continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension,
or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said
Hitachi, Ltd., and Hitachi Information Technology Co.,Ltd

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) <u>Yoshihiro Iwai</u>	<u>May. 29, 2003</u>
2) <u>Tatsuki Ishii</u>	<u>May. 29, 2003</u>
3) <u>Kenji Shizōka</u>	<u>May. 29, 2003</u>
4) <u>Hirotake Tokuyama</u>	<u>May 28, 2003</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____

RECORDED: 06/16/2003

PATENT
REEL: 014159 FRAME: 0278